

# FDPF320N06L

## N-Channel Logic Level PowerTrench® MOSFET

60 V, 21 A, 25 mΩ

### Features

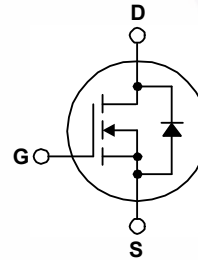
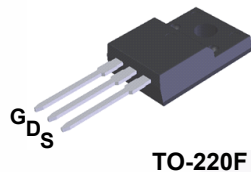
- $R_{DS(on)} = 20\text{ m}\Omega$  (Typ.) @  $V_{GS} = 10\text{ V}$ ,  $I_D = 21\text{ A}$
- $R_{DS(on)} = 23\text{ m}\Omega$  (Typ.) @  $V_{GS} = 5\text{ V}$ ,  $I_D = 17\text{ A}$
- Low Gate Charge (Typ. 23.2 nC)
- Low  $C_{rss}$  (Typ. 64 pF)
- Fast Switching Speed
- 100% Avalanche Tested
- Improved dv/dt Capability
- RoHS Compliant

### Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

### Applications

- Consumer Appliances
- LCD/LED/PDP TV



### MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	FDPF320N06L	Unit
$V_{DSS}$	Drain to Source Voltage	60	V
$V_{GSS}$	Gate to Source Voltage	$\pm 20$	V
$I_D$	Drain Current	- Continuous ( $T_C = 25^\circ\text{C}$ )	21
		- Continuous ( $T_C = 100^\circ\text{C}$ )	15
$I_{DM}$	Drain Current	- Pulsed (Note 1)	84
$E_{AS}$	Single Pulsed Avalanche Energy	(Note 2)	66
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6.0
$P_D$	Power Dissipation	( $T_C = 25^\circ\text{C}$ )	26
		- Derate Above $25^\circ\text{C}$	0.17
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +175	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds	300	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	FDPF320N06L	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	5.8	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	

## Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDPF320N06L	FDPF320N06L	TO-220F	Tube	N/A	N/A	50 units

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250 \mu\text{A}, V_{GS} = 0 \text{ V}$	60	-	-	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$ , Referenced to $25^\circ\text{C}$	-	0.04	-	$\text{V}/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 48 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 48 \text{ V}, T_C = 150^\circ\text{C}$	-	-	1 500	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	$\pm 100$	$\mu\text{A}$

### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu\text{A}$	1.0	-	2.5	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 21 \text{ A}$ $V_{GS} = 5 \text{ V}, I_D = 17 \text{ A}$	-	20 23	25 38	$\text{m}\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_D = 21 \text{ A}$	-	34	-	S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}$ $f = 1 \text{ MHz}$	-	1105	1470	pF
$C_{oss}$	Output Capacitance		-	115	150	pF
$C_{rss}$	Reverse Transfer Capacitance		-	64	-	pF
$Q_{g(tot)}$	Total Gate Charge at 10V	$V_{GS} = 10 \text{ V}$	-	23.2	30.2	nC
$Q_{g(tot)}$	Total Gate Charge at 5V	$V_{GS} = 5 \text{ V}$	-	12.7	16.5	nC
$Q_{gs}$	Gate to Source Gate Charge	$V_{DS} = 48 \text{ V}$ , $I_D = 21 \text{ A}$	-	3.4	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge	(Note 4)	-	6.3	-	nC

### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 30 \text{ V}, I_D = 21 \text{ A}$ , $V_{GS} = 5 \text{ V}, R_G = 4.7 \Omega$	-	16	42	ns
$t_r$	Turn-On Rise Time		-	34	78	ns
$t_{d(off)}$	Turn-Off Delay Time		-	27	64	ns
$t_f$	Turn-Off Fall Time		(Note 4)	-	8	26
ESR	Equivalent Series Resistance (G-S)	$f = 1 \text{ MHz}$	-	2	-	$\Omega$

### Drain-Source Diode Characteristics

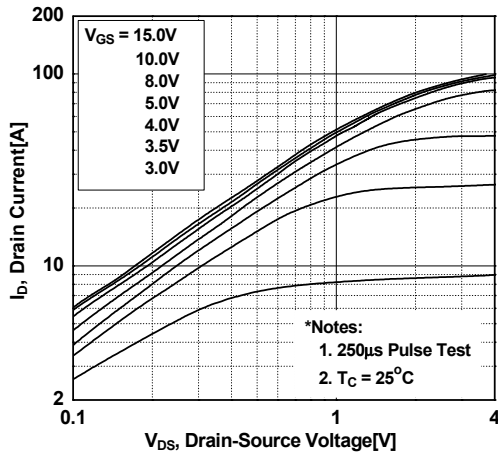
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	21	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	84	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{SD} = 21 \text{ A}$	-	-	1.3	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{SD} = 21 \text{ A}, V_{DD} = 48 \text{ V}$ , $di_F/dt = 100 \text{ A}/\mu\text{s}$	-	27	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	23	-	nC

#### Notes:

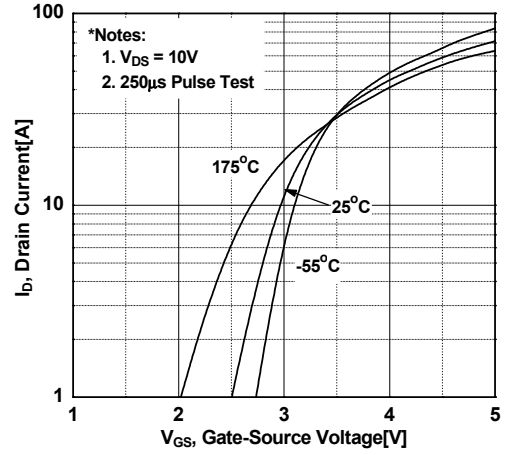
1. Repetitive rating; pulse-width limited by maximum junction temperature.
2.  $L = 1 \text{ mH}, I_{AS} = 11.5 \text{ A}, R_G = 25 \Omega$ , starting  $T_J = 25^\circ\text{C}$ .
3.  $I_{SD} \leq 21 \text{ A}, di/dt \leq 200 \text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$ , starting  $T_J = 25^\circ\text{C}$ .
4. Essentially independent of operating temperature typical characteristics.

## Typical Performance Characteristics

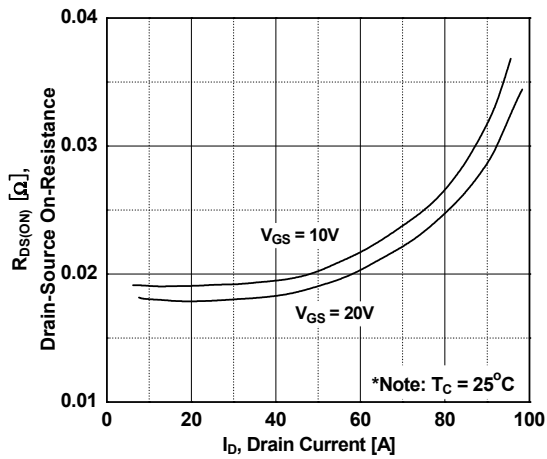
**Figure 1. On-Region Characteristics**



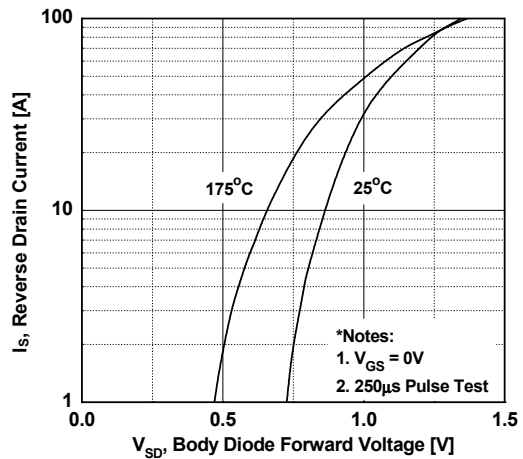
**Figure 2. Transfer Characteristics**



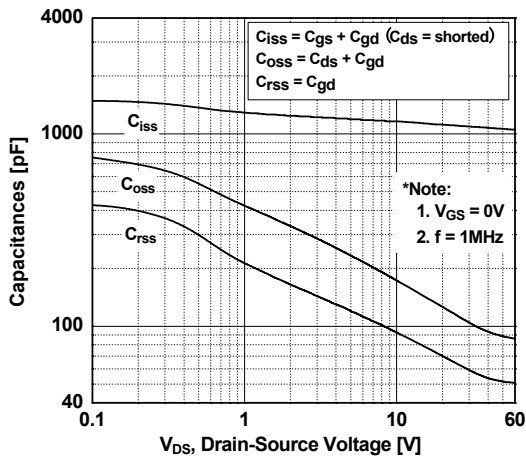
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



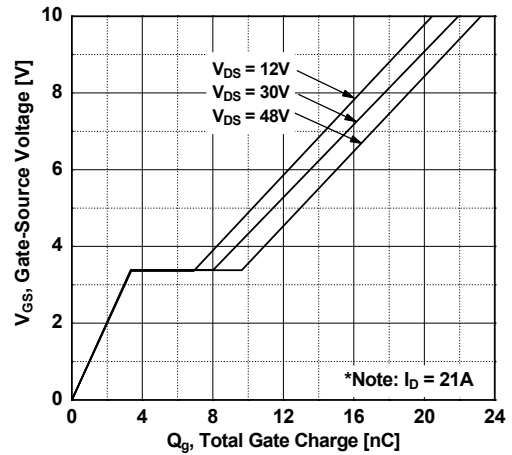
**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**



**Figure 5. Capacitance Characteristics**

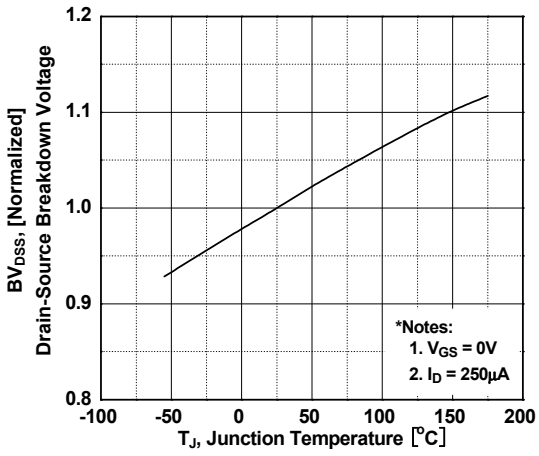


**Figure 6. Gate Charge Characteristics**

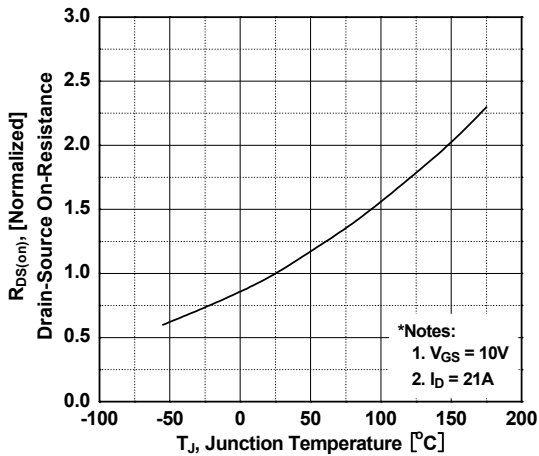


**Typical Performance Characteristics** (Continued)

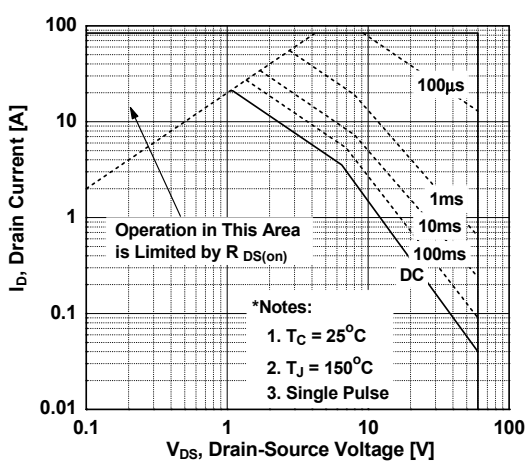
**Figure 7. Breakdown Voltage Variation vs. Temperature**



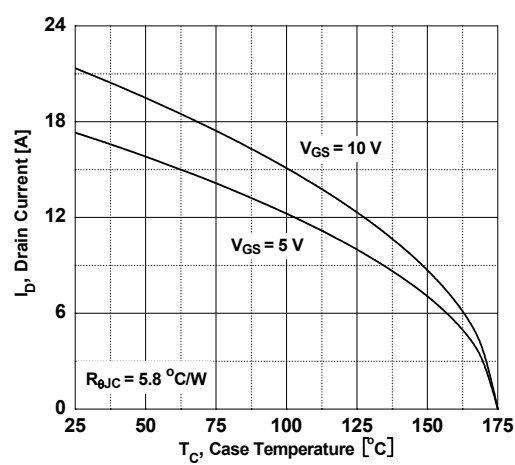
**Figure 8. On-Resistance Variation vs. Temperature**



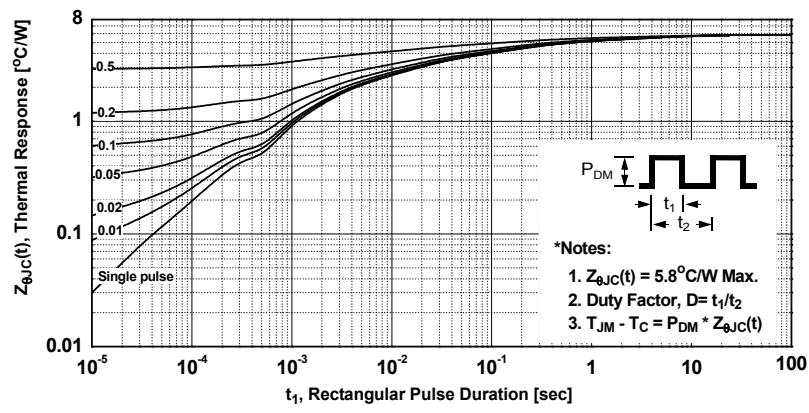
**Figure 9. Maximum Safe Operating Area**

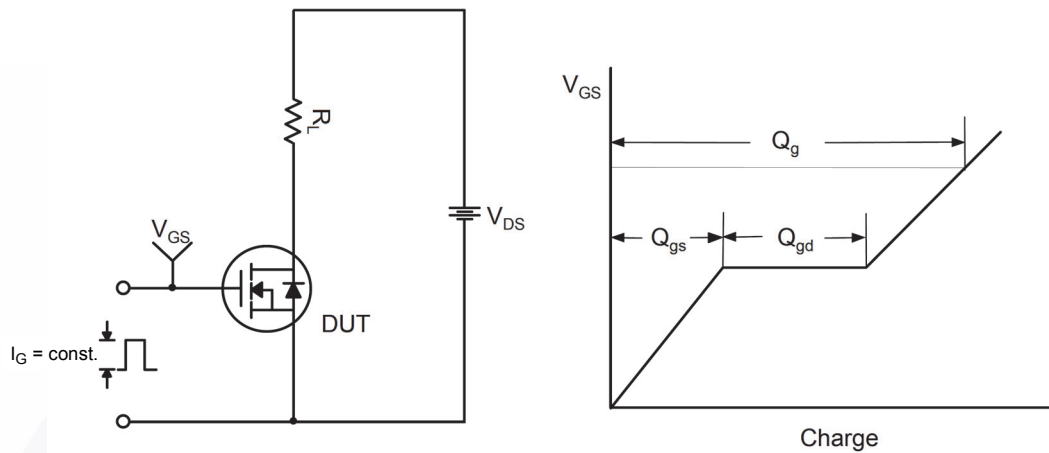


**Figure 10. Maximum Drain Current vs. Case Temperature**

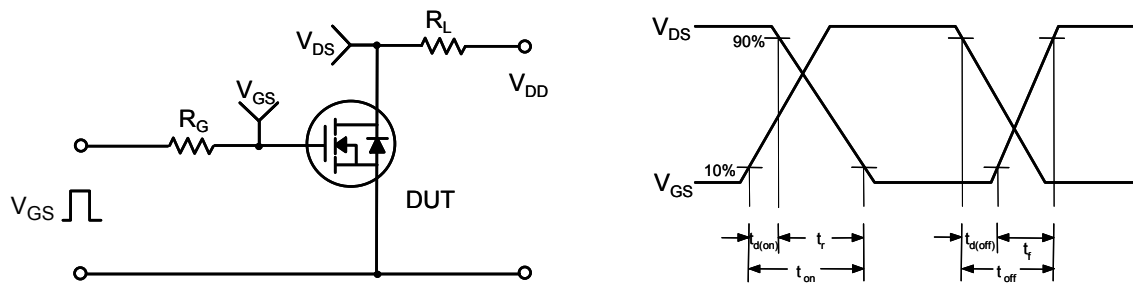


**Figure 11. Transient Thermal Response Curve**

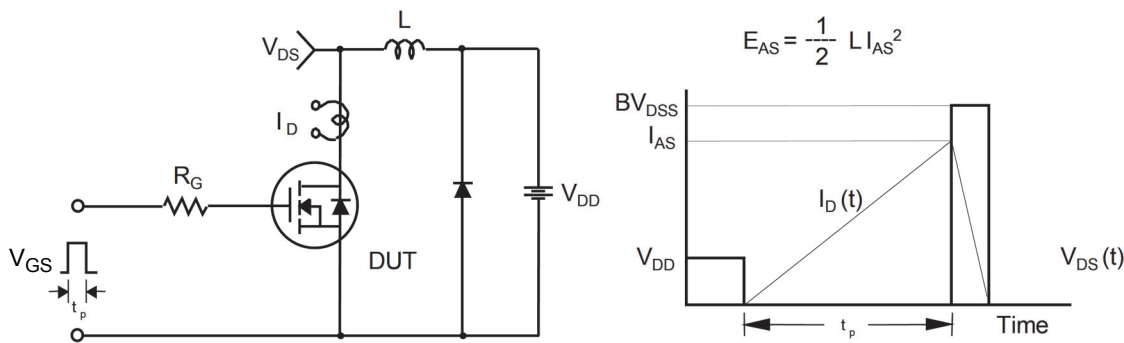




**Figure 12. Gate Charge Test Circuit & Waveform**



**Figure 13. Resistive Switching Test Circuit & Waveforms**



**Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms**

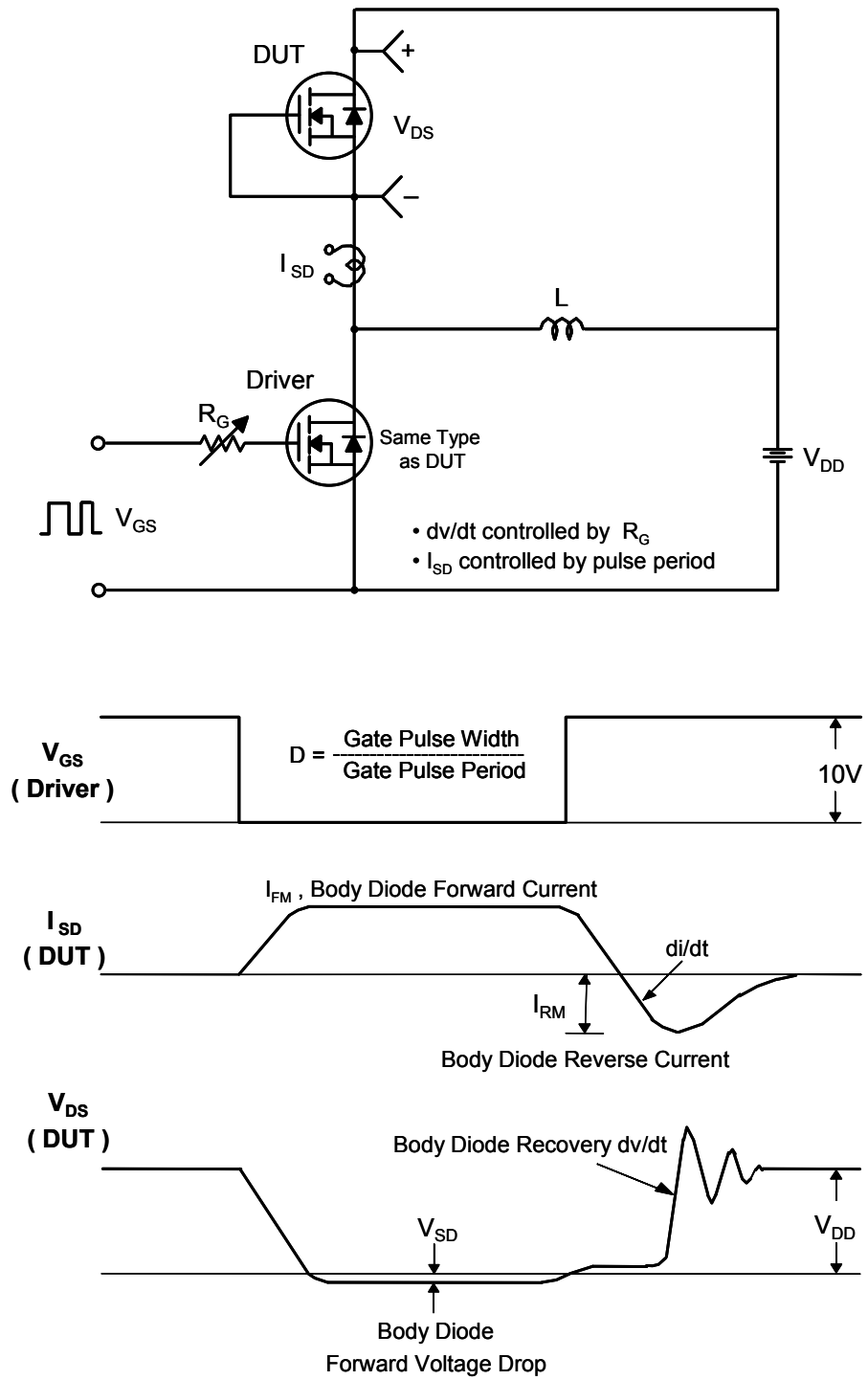
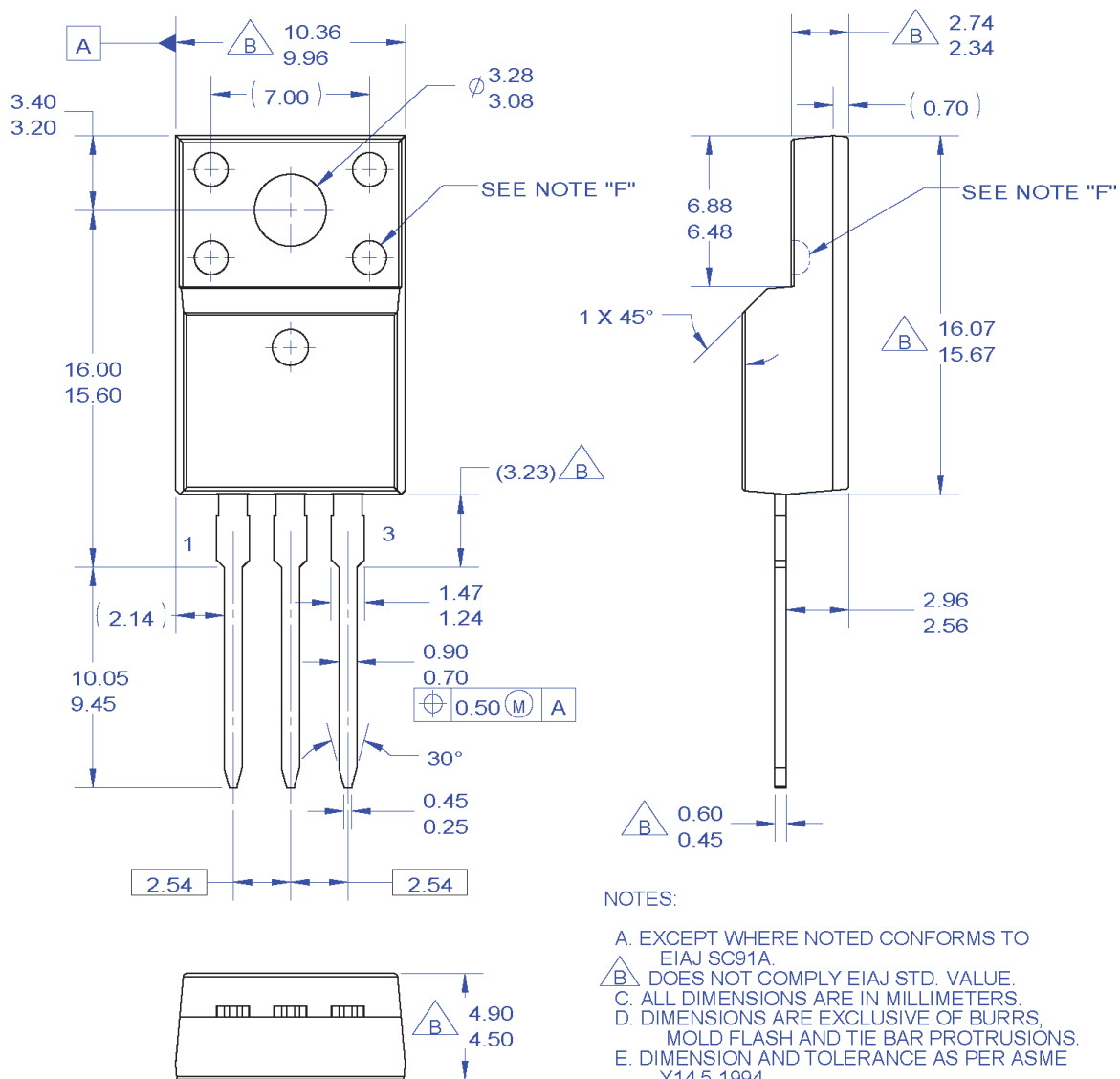


Figure 15. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms

### Mechanical Dimensions



**Figure 16. TO220, Molded, 3-Lead, Full Pack, EIAJ SC91, Straight Lead**

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